

MMB460A - Preliminary

4.5-4.7Hz MMB Series TDD BPF

Features

- Low Loss with High Rejection
- Universal footprint across family for all TDD bands

Applications

- Wireless Infrastructure applications
- High-performance carrier-grade TDD Pico-cells.



Part Dimensions: 40.0 × 5.0 × 9.3 mm • 4.8 g
Materials: Ag plated ceramic block with tin plated brass shield

Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared to other bandpass filter technologies.

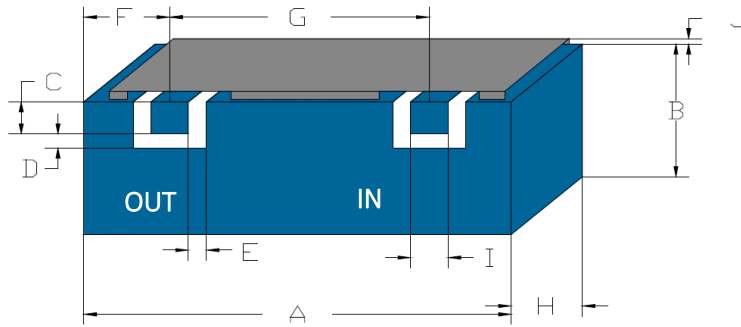
Electrical Specifications

| Parameter | Frequency (MHz) | Typical at 25°C | Spec. at 25°C | Spec. over -40°C to +85°C |
|--------------------------------------|-----------------|-----------------|---------------|---------------------------|
| Nominal Impedance | - | 50 ohms | - | - |
| Average Input Power | - | - | - | 10.0 Watt max |
| Peak Input Power | - | - | - | 100 Watt max |
| Input-Output Response | | | | |
| Passband Insertion Loss (20 MHz avg) | 4500-4700 | 1.7 dB | 1.9 dB max | 2.0 dB max |
| Passband Ripple | 4500-4700 | 1.0 dB | 1.4 dB max | 1.5 dB max |
| Passband Return Loss | 4500-4700 | 14 dB | 13 dB min | 12 dB min |
| Attenuation: | 1-4100 | 55 dB | 50 dB min | 50 dB min |
| | 4101-4400 | 32 dB | 30 dB min | 30 dB min |
| | 4400-4460 | 22 dB | 20 dB min | 20 dB min |
| | 4740-4800 | 22 dB | 20 dB min | 20 dB min |
| | 4800-5170 | 32 dB | 30 dB min | 30 dB min |
| | 5170-5950 | 55 dB | 50 dB min | 50 dB min |

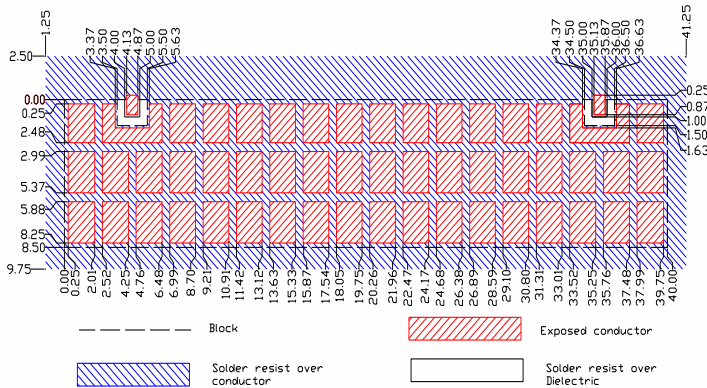
Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

| Specification Allowance | |
|-------------------------|--------|
| Insertion Loss | 0.1 dB |
| Return Loss | 1.0 dB |
| Attenuation | 1.0 dB |

Mechanical Drawing



PCB Layout



| Dim. | Nominal (mm) | Tolerance (±mm or Max) |
|------|-----------------|---------------------------|
| A | 39.7 | 0.30 |
| B | 3.1 | 0.30 |
| C | 1.0 | 0.13 |
| D | 0.5 | 0.13 |
| E | 0.5 | 0.13 |
| F | 4.5 | 0.25 |
| G | 31.0 | 0.13 |
| H | 9.3 | max |
| I | 1.0 | 0.13 |
| J | 1.4 | 0.2 |

IMPORTANT: Please assure ≥ 30 mils (0.75mm) thickness of dielectric beneath the I/O Pads and the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

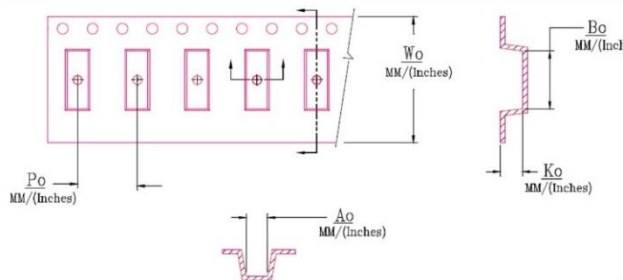
Recommended solder: 6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

Packaging and Marking

| Dimension | Units | Spec. |
|---------------|-------|-------|
| Reel Diameter | mm | 330 |
| Reel Weight | kg | |
| Reel Quantity | ea. | 250 |

Product Marking

CTS
460
YWW



| W_0 | A_0 | B_0 | K_0 | P_0 |
|---------------------|--------------------|---------------------|--------------------|---------------------|
| 2.205 in 56.0 mm | 0.213 in 5.4 mm | 1.587 in 40.3 mm | 0.378 in 9.6 mm | 0.630 in 16.0 mm |

Electrical Response

